

SOT470-1

plastic thermal enhanced low profile quad flat package; 100 leads; body 14 x 14 x 1.4 mm; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP100
Package type industry code	HLQFP100
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	20-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	13.9	-	14	14.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	[tbd]	-	[tbd]	1.6	mm
A ₂	package height	1.3	-	1.4	1.5	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	100	-	

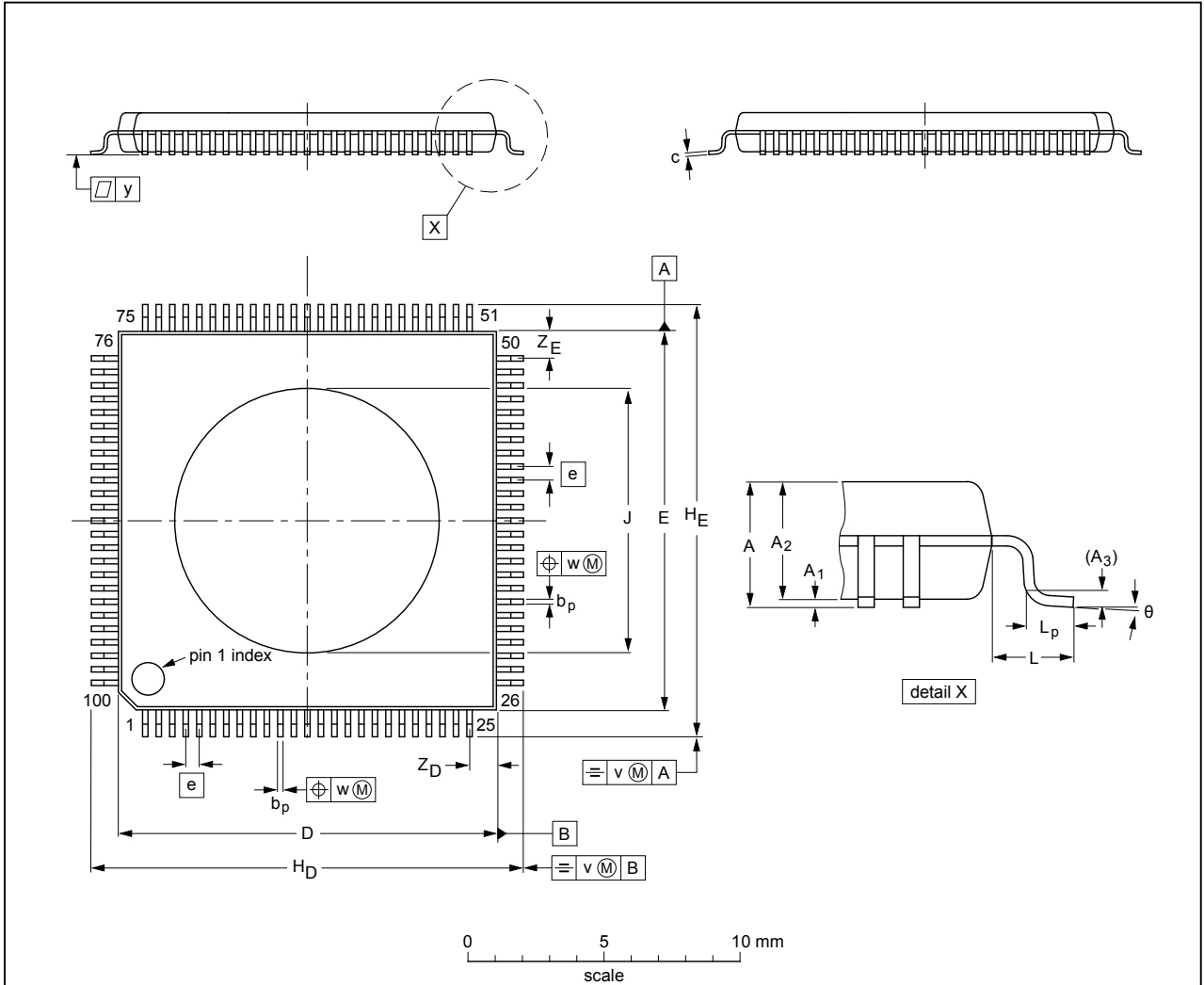


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2. Package outline

HLQFP100: plastic thermal enhanced low profile quad flat package; 100 leads; body 14 x 14 x 1.4 mm; heatsink

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _D	H _E	J ⁽²⁾	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	1.6	0.20 0.05	1.5 1.3	0.25	0.28 0.16	0.18 0.12	14.1 13.9	14.1 13.9	0.5	16.25 15.75	16.25 15.75	10.15 9.15	1	0.75 0.45	0.2	0.12	0.1	1.15 0.85	1.15 0.85	7° 0°

Notes

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.
2. Heatsink intrusion 0.0127 maximum.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT470-1						97-01-13 03-02-20

Fig. 1. Package outline HLQFP100 (SOT470-1)

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3. Legal information

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